

20A, 650V SiC Merged PIN Schottky Diode

FEATURES

- Max junction temperature 175°C
- MPS structure for high ruggedness to forward current surge events
- High-speed switching possible
- High forward surge capability
- High-frequency operation
- Positive temperature coefficient on V_F
- RoHS compliant
- Halogen-free

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|------------------|---|----|---|---|---|---|---|-----|----|
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| $\boldsymbol{-}$ | | | _ | • | _ | | u | 4 1 | -3 |

- General purpose
- Switch mode power supplies
- Power factor correction

MECHANICAL DATA

• Case: TO-220AC-2L

Molding compound meets UL 94V-0 flammability rating

• Terminal: Matte tin plated leads, solderable per J-STD-002

Polarity: As circuit diagram

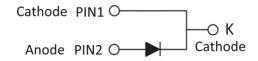
• Weight: 2.03g (approximately)

| KEY PARAMETERS | | | | | |
|--------------------|-------------|------|--|--|--|
| PARAMETER | VALUE | UNIT | | | |
| l _F | 20 | Α | | | |
| V_{RRM} | 650 | V | | | |
| I _{FSM} | 128 | Α | | | |
| T _{J MAX} | 175 | °C | | | |
| Package | TO-220AC-2L | | | | |
| Configuration | Single die | | | | |





TO-220AC-2L



| ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted) | | | | | |
|---|------------------------|-------------|------|---|--|
| PARAMETER | SYMBOL | VALUE | UNIT | | |
| Repetitive peak reverse voltage | V _{RRM} | 650 | V | | |
| Reverse voltage, total rms value | V _{R(RMS)} | 455 | V | | |
| Continuous Rectified Forward Current @ T _J = | I _F | 20 | Α | | |
| Surge peak forward current 10ms single half | $T_C = 25^{\circ}C$ | , | 128 | Α | |
| sine-wave superimposed on rated load | T _C = 125°C | IFSM | 108 | Α | |
| Junction temperature | TJ | -55 to +175 | °C | | |
| Storage temperature | T _{STG} | -55 to +175 | °C | | |



| THERMAL PERFORMANCE | | | | | | |
|-------------------------------------|--------|------|------|------|--|--|
| PARAMETER | SYMBOL | TYP | MAX | UNIT | | |
| Junction-to-case thermal resistance | Rejc | 0.68 | 0.82 | °C/W | | |

| ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted) | | | | | |
|--|--|------------------|-------|------|------|
| PARAMETER | CONDITIONS | SYMBOL | TYP | MAX | UNIT |
| | I _F = 10A, T _J = 25°C | VF | 1.17 | - | V |
| | I _F = 20A, T _J = 25°C | | 1.38 | 1.45 | V |
| Forward voltage(1) | $I_F = 10A, T_J = 150$ °C | | 1.19 | - | V |
| Forward voltage ⁽¹⁾ | I _F = 20A, T _J = 150°C | | 1.56 | - | V |
| | I _F = 10A, T _J = 175°C | | 1.22 | - | V |
| | I _F = 20A, T _J = 175°C | | 1.64 | 1.85 | V |
| Payers aurrent @ rated V-(2) | T _J = 25°C | 1_ | - | 20 | μA |
| Reverse current @ rated V _R ⁽²⁾ | T _J = 175°C | - I _R | - | 200 | μA |
| | $f = 1MHz, V_R = 1V$ | | 945 | - | pF |
| Junction capacitance | $f = 1MHz, V_R = 200V$ | С | 134.5 | - | pF |
| | f = 1MHz, V _R = 400V | | 92.7 | - | pF |
| Capacitive Charge | V _R = 400V | Qc | 65.6 | - | nC |

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

| ORDERING INFORMATION | | | | | |
|----------------------|-------------|-----------|--|--|--|
| ORDERING CODE | PACKAGE | PACKING | | | |
| TSCDT20065G1 | TO-220AC-2L | 50 / Tube | | | |



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig.1 Typical Forward Characteristics

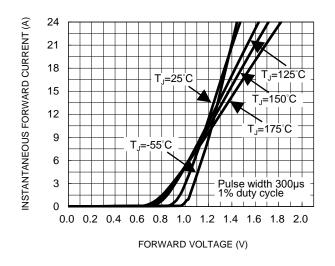


Fig.3 Peak forward current versus case temperature

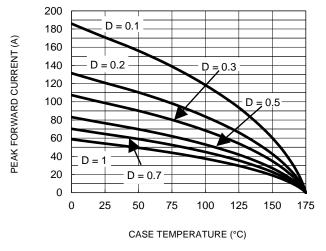


Fig.5 Typical Capacitive Charge

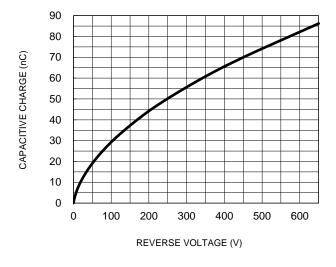


Fig.2 Typical Reverse Characteristics

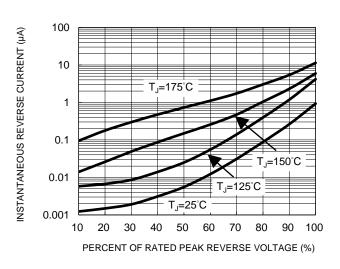


Fig.4 Typical Junction Capacitance

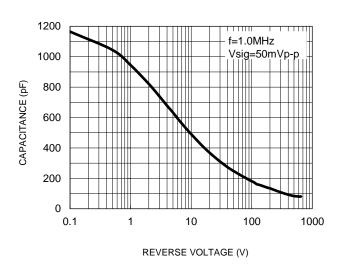
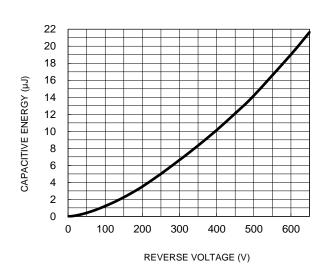


FIG.6 Typical Capacitance Stored Energy



Version: A2404

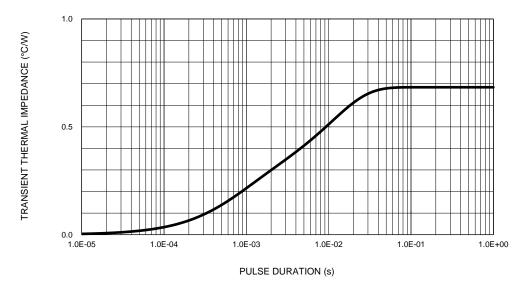
3



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

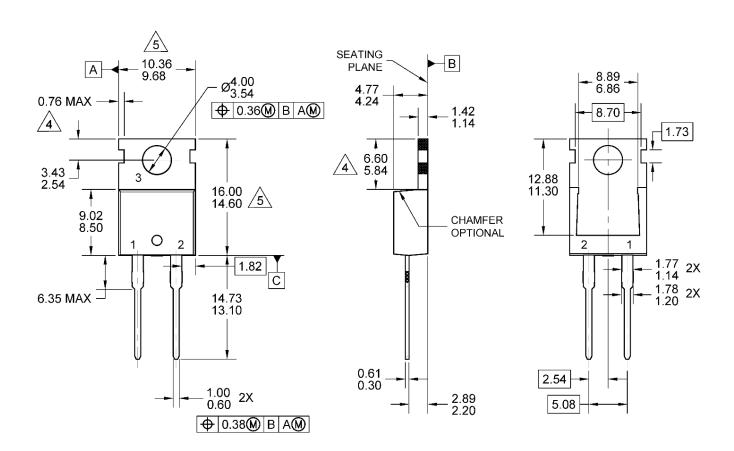
Fig.7 Typical Transient Thermal Characteristics

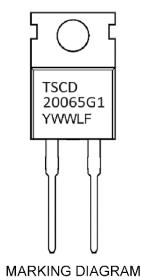




PACKAGE OUTLINE DIMENSIONS

TO-220AC-2L





Υ

WW = WEEK CODE (01~52)
L = LOT CODE (1~9, A~Z)

F = FACTORY CODE

= YEAR CODE

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PACKAGE OUTLINE REFERENCE: JEDEC TO-220, VARIATION AC, ISSUE K.
- THE DEFINED ZONE WHERE STAMPING AND SINGULATION IRREGULARITIES ARE ALLOWED. SLOT AND NOTCH MAY APPEAR IN THIS ZONE.
- THIS DO NOT INCLUDE MOLD FLASH.
 THESE DIMENSIONS ARE MEASURED AT
 THE OUTERMOST EXTREME OF THE
 PLASTIC BODY.
- 6. DWG NO REF: HQ2SD07-TO220ACSiC-119 REV A.



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